Attorney Docket No. 291958162US

P Date:		12/02	By: V Nels	29 Alm	se /		
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IN RE	APPLICATIO	N OF. RITZDORF ET AL.	EXAMINER ART UNIT:	DEVAN IVI. C	OLLINS 30 TI		
Δ DDI		: 09/018,783		2023 ATION No.: 1242			
	EBRUARY	•	CONFIRMA	(110N NO., 1242	ER 2		
	METHOD! MICRO-ST METALLIZ/ PRODUCT	FOR FILLING RECESSED RUCTURES WITH ATION IN THE		·	RECEIVED 2002 AUG 30 2002 TECHNOLIZAY CENTER 2800		
_	missioner fo hington, D.C						
1.	Timing of	Submission					
	The information transmitted herewith is being filed <i>after</i> three months of the filing date of this application or after the mailing date of the first Office action on the merits whichever occurred last, but <i>before</i> the mailing date of either a final action under 37 CFR 1.113 or a Notice of Allowance under 37 CFR 1.311, whichever occurs first. The references listed on the enclosed Form PTO/SB/08A may be material to the examination of this application; the Examiner is requested to make them of record in the application.						
2.	Cited Info						
	⊠ Co	pies of the following refere	nces are enclosed	:			
		All cited references References marked by The following:	<i>r</i> asterisks				
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	Copies of the following references can be found in parent application Ser. No.					
		All cited references References marked by asterisks The following:				
	The following references are not in English. For each such reference, the undersigned has enclosed: (i) a translation of the reference; (ii) a copy of a communication from a foreign patent office or International Searching Authority citing the reference; (iii) a copy of a reference which appears to be an English-language counterpart; or (iv) an English-language abstract for the reference prepared by a third party. Applicant has not verified that the translation, English-language counterpart or third-party abstract is an accurate representation of the teachings of the non-English reference, though, and reserves the right to demonstrate otherwise.					
		All cited references References marked by ampersands The following:				
<u>Effect</u>	of Info	rmation Disclosure Statement (37 CFR 1.97(h))				
(i) a s applic third p be, m item reserv	earch hation dearties and terial of information inform	tion Disclosure Statement is not to be construed as a representation that: has been made; (ii) additional information material to the examination of this does not exist; (iii) the information, protocols, results and the like reported by are accurate or enabling; or (iv) the cited information is, or is considered to to patentability. In addition, applicant does not admit that any enclosed formation constitutes prior art to the subject invention and specifically right to demonstrate that any such reference is not prior art.				
Fee F	<u>aymen</u>	t (37 CFR 1.97(c)) or Certification (37 CFR 1.97(e))				
\boxtimes	Applic	cant elects to pay the fee under 37 CFR 1.17(p) \$180.00.				
		Check enclosed for \$180.00 Please charge the above fee(s) to Deposit Account No. 50-0665 this paper is provided in triplicate.				
		cant submits that no fee is due in light of the following certification under 37 1.97(e) (check only one):				
		In accordance with 37 CFR 1.97(e)(1), the undersigned hereby states that each item of information submitted herewith was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to this filing of this statement; or				
		In accordance with 37 CFR 1.97(e)(2), the undersigned hereby states that no item of information submitted herewith was cited in a communication from a foreign patent office in a counterpart foreign application, or, to the knowledge of the person signing the certification				

3.

4.

after making reasonable inquiry, was known to any individual designated in 37 CFR 1.56(c), more than three months prior to the filing of this statement.

Please charge any underpayment for timely filing of this paper to Deposit Account No. 50-0665.

5. Patent Term Adjustment (37 CFR 1.704(d))

The undersigned states that each item of information submitted herewith was cited in a communication from a foreign patent office in a counterpart application and that this communication was not received by any individual designated in 37 C.F.R. §1.56(c) more than thirty days prior to the filing of this statement. 37 C.F.R. §1.704(d).

Date: 8/12/2002

Respectfully submitted, Perkins Coie LLP

Paul T. Parker

Registration No. 38,264

Correspondence Address:

Customer No. 25096 Phone: (206) 583-8888



INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Form PTO-1449 (Modified) (Use several sheets if necessary)

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Co UPLETE IF KNOWN				
Application Number	09/018,783			
Confirmation Number	1242			
Filing Date	February 4, 1998			
First Named Inventor	Thomas L. Ritzdorf			
Group Art Unit	2823			
Examiner Name	Deven M. Collins			
Attorney Docket No.	291958162US			

				-			U.S. PATENT DOCUMENTS			
Examiner Initials	Cif No		U.S. Patent or Application Kind Code NUMBER (if known)		ode	Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Figures Appear		
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Examiner Initials	Cite No.						or (in CAPITAL LETTERS), title of the article rial, symposium, catalog, etc.), date, page(s), and/or country where published.			Т
		AHN, E. C. et al. "Adhesion Reliability of Cu-Cr Alloy Films to Polyimide" Materials Research Society Symposium Proceedings, 1996, Vol. 427, pp. 141-145, Materials Research Society.								
		anı	neal		dama		ff between reliability and post-CMF interconnects" <i>IEEE International</i>			
		GLADKIKH, A. et al. "Activation Energy of Electromigration in Copper Thin Film Conductor Lines" Materia!s Research Society Symposium Proceedings, 1996, Vol. 427, pp. 121-126, Materials Research Society.								
		KONONENKO, O. V. ct al. "Electromigration In Submicron Wide Copper Lines" Materials Research Society Symposium Proceedings, 1996, Vol. 427, pp. 127-132, Materials Research Society.								
•		MEI, Y. et al. "Thermal Stability and Interaction Between SIOF and Cu Film" Materials Research Society Symposium Proceedings, 1996, Vol. 427, pp. 433-439, Materials Research Society.								
		RUSSELL, S. W. et al. "The Effect of Copper on the Titanium-Silicon Dioxide Reaction and the Implications for Self-Encapsulating, Self-Adhering Metallization Lines", <i>Materials Research Society Symposium Proceedings</i> , 1992, Vol. 260, pp. 763-768, Materials Research Society, Pittsburgh, PA.								

EXAMINER		DATE CONSIDERED				
*EXAMINER:	Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not					
	considered. Include copy of this form with next communication to application(s).					